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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10084923	03/01/2002	751 438	751	2812	Williams

****APPLICANTS:** Taniguchi Osamu; Miyashita Tomoko; Yamagishi Yasuo; Omote Koji;
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****CONTINUING DATA VERIFIED:**

NONE WB

**** FOREIGN APPLICATIONS VERIFIED:**

JAPAN 2001-262359 08/30/2001 WB

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☒ yes ☐ no
35 USC 119 conditions met ☒ yes ☐ no
Verified and Acknowledged Examiners's initials WB

ATTORNEY DOCKET NO

020255

TITLE: Thin-film circuit substrate and manufacturing method thereof, and a via formed substrate and manufacturing method thereof

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Final Claim for O.G.
ISSUE FEE			
Amount Due	Date Paid		
		PREPARED FOR ISSUE	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
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